



Parameter	Rating	Units
Blocking Voltage	250	V _P
Load Current	1	A _{DC}
On-Resistance (max)	0.75	Ω

Features

- Handle Load Currents Up to 1A_{DC}
- 2500V_{rms} Input/Output Isolation
- Power SIP Package
- High Reliability
- Low Drive Power Requirements
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Flammability Rating UL 94 V-0

Applications

- Industrial Controls
- Motor Control
- Robotics
- Medical Equipment—Patient/Equipment Isolation
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- IC Equipment
- Home Appliances

Description

IXYS Integrated Circuits Division and IXYS have combined to bring OptoMOS® technology, reliability and compact size to a new family of high power solid state relays. As part of that family, the CPC1726 is a normally open (1-Form-A) solid state relay. The CPC1726 employs optically coupled MOSFET technology to provide 2500V_{rms} of input to output isolation.

The optically coupled outputs, that use patented OptoMOS architecture, are controlled by a highly efficient infrared LED. The combination of low on-resistance and high load current handling capabilities makes the relay suitable for a variety of high performance switching applications.

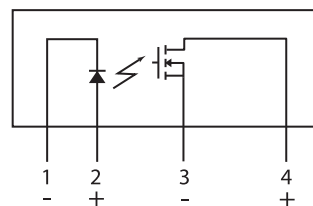
Approvals

- UL 508 Certified Component: File E69938
- CSA Certified Component: Certificate 1172007

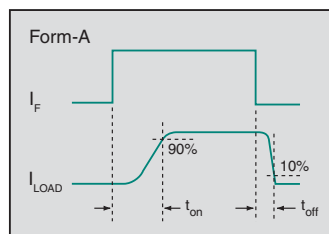
Ordering Information

Part #	Description
CPC1726Y	4-Pin (8-Pin Body) Power SIP Package (25 per tube)

Pin Configuration



Switching Characteristics of Normally Open Devices



Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	250	V _P
Reverse Input Voltage	5	V
Input control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation ¹	150	mW
Total Power Dissipation ²	1600	mW
Isolation Voltage, Input to Output	2500	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 3.33 mW / °C

² Derate linearly 16.667 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C

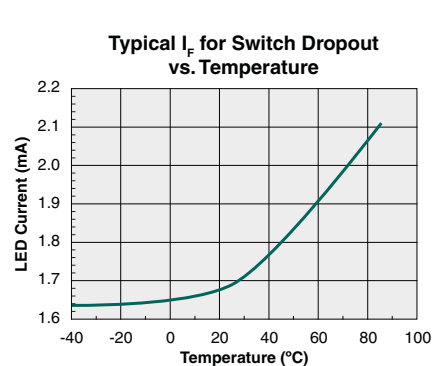
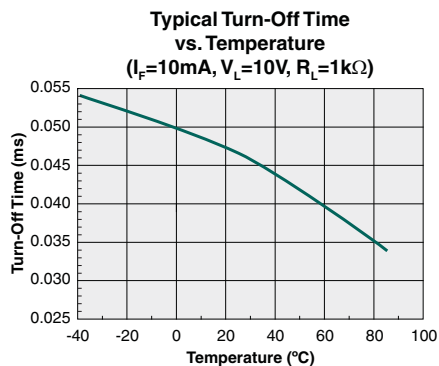
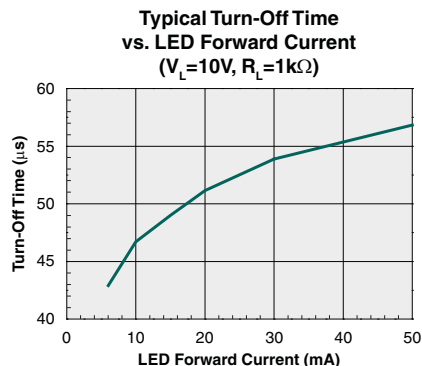
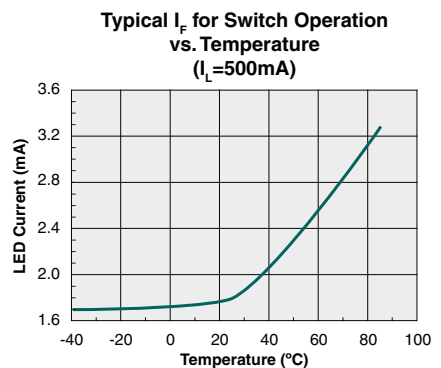
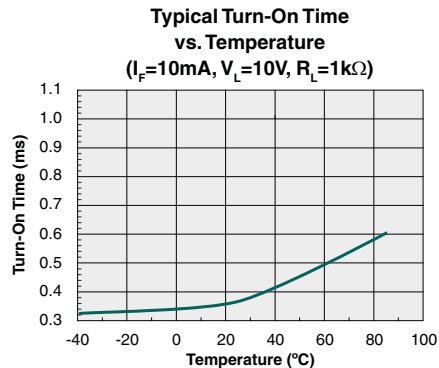
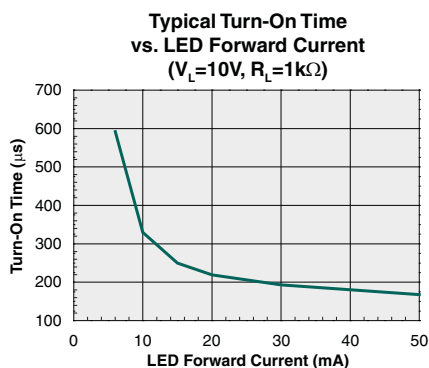
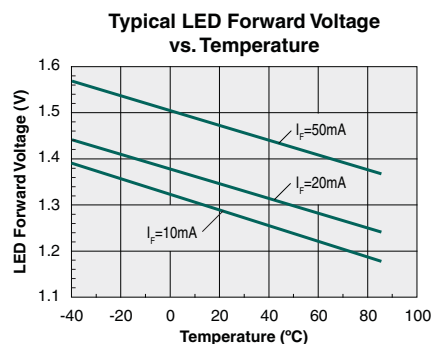
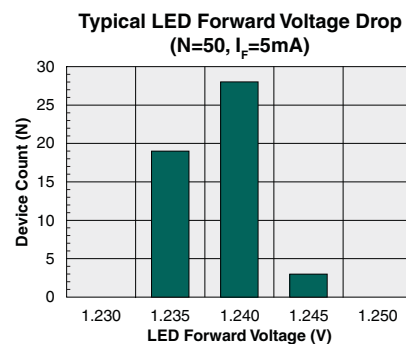
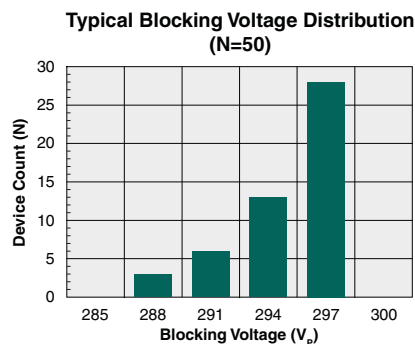
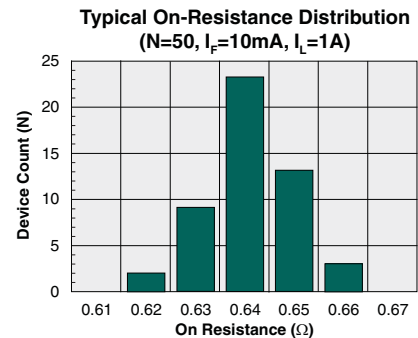
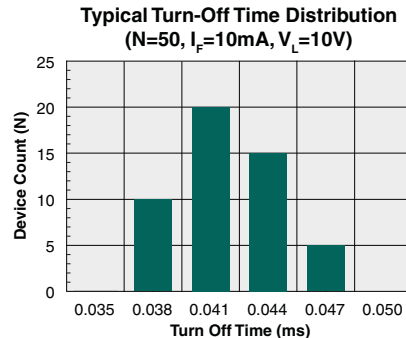
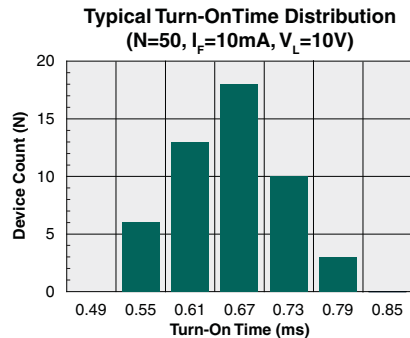
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current, Continuous	Free air	I _L	-	-	1	A _{DC}
Peak Load Current	t=10ms	I _{LPK}	-	-	3	A
On-Resistance ¹	I _L =1A	R _{ON}	-	0.64	0.75	Ω
Off-State Leakage Current	V _L =250V _P	I _{LEAK}	-	-	1	μA
Switching Speeds	I _F =10mA, V _L =10V	t _{on}	-	0.67	5	ms
Turn-On			-	0.04	2	
Turn-Off		t _{off}	-	0.04	2	
Output Capacitance	I _F =0mA, V _L =50V, f=1MHz	C _{OFF}	-	60	-	pF
Input Characteristics						
Input Control Current to Activate	I _L =1A	I _F	-	1.8	10	mA
Input Control Current to Deactivate	-	I _F	0.6	-	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Input/Output Characteristics						
Capacitance, Input to Output	V _{IO} =0V, f=1MHz	C _{IO}	-	2	-	pF

¹ Measurement taken within 1 second of on-time.

Thermal Characteristics

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Thermal Impedance (junction to case)	-	R _{θJC}	-	1.5	-	°C/W

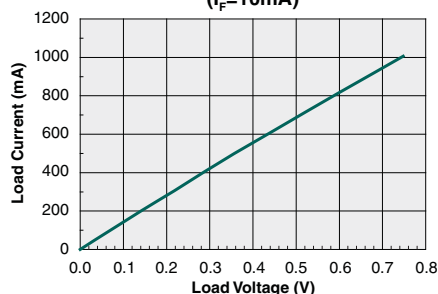
PERFORMANCE DATA @25°C (Unless Otherwise Noted)*



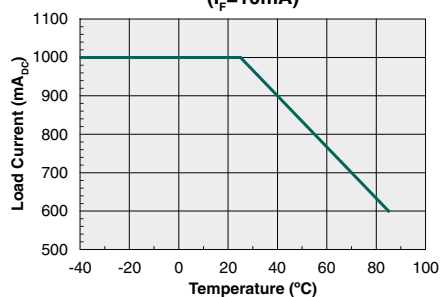
*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA @25°C (Unless Otherwise Noted)*

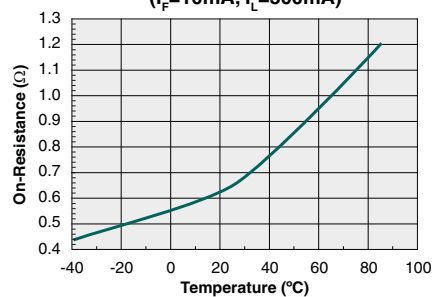
**Typical Load Current
vs. Load Voltage
($I_F=10\text{mA}$)**



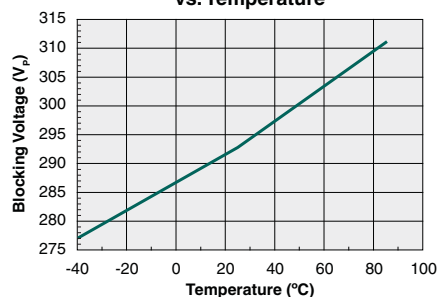
**Maximum Load Current
vs. Temperature
($I_F=10\text{mA}$)**



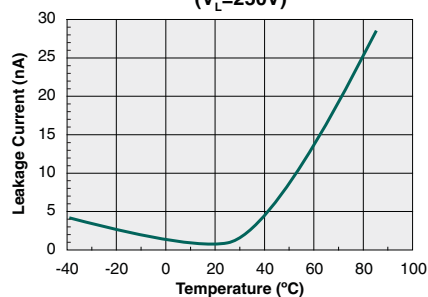
**Typical On-Resistance vs. Temperature
($I_F=10\text{mA}$, $I_L=500\text{mA}$)**



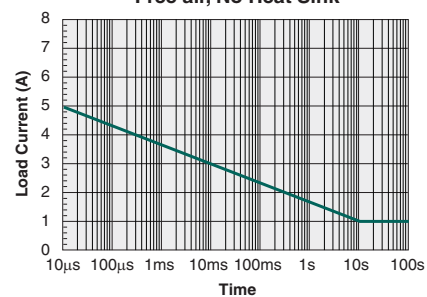
**Typical Blocking Voltage
vs. Temperature**



**Leakage Current vs. Temperature
Measured Across Pins 3 & 4
($V_L=250\text{V}$)**



**Energy Rating Curve
Free air, No Heat Sink**



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard IPC/JEDEC J-STD-033.

Device	Moisture Sensitivity Level (MSL) Classification
CPC1726Y	MSL 1

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Soldering Profile

Provided in the table below is the Classification Temperature (TC) of this product and the maximum dwell time the body temperature of this device may be above (TC - 5)°C. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through hole devices, and any other processes, the guidelines of J-STD-020 must be observed.

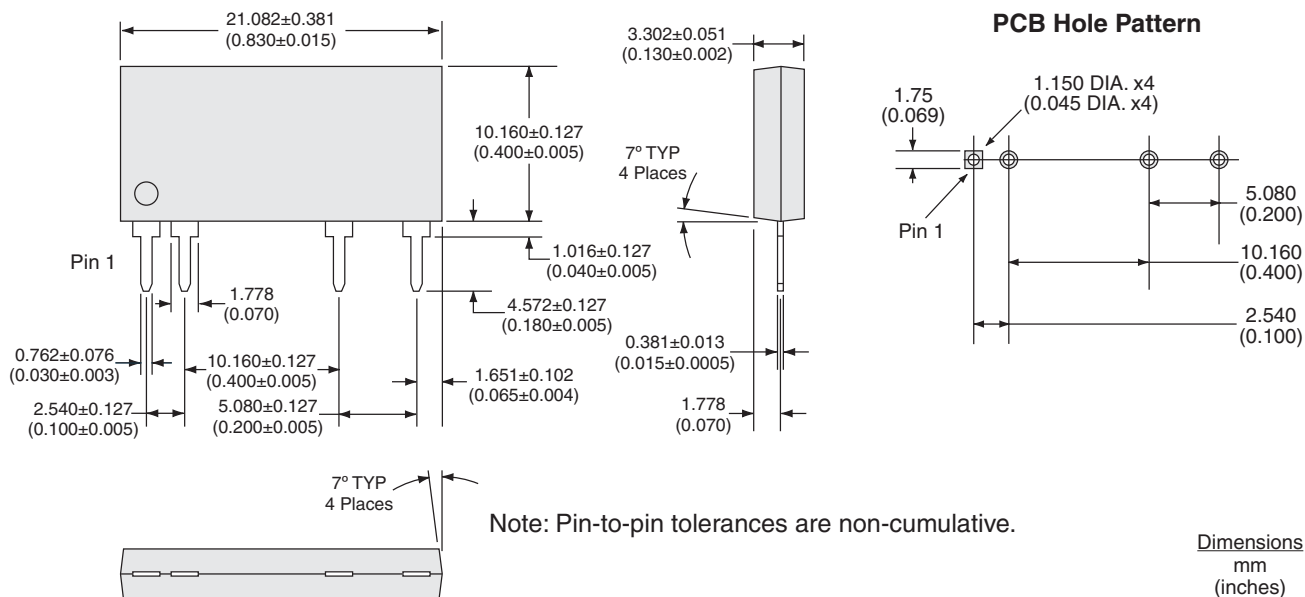
Device	Classification Temperature (T _c)	Dwell Time (t _p)	Max Reflow Cycles
CPC1726Y	245°C	30 seconds	1

Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.



MECHANICAL DIMENSIONS



For additional information please visit our website at: www.ixysic.com

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